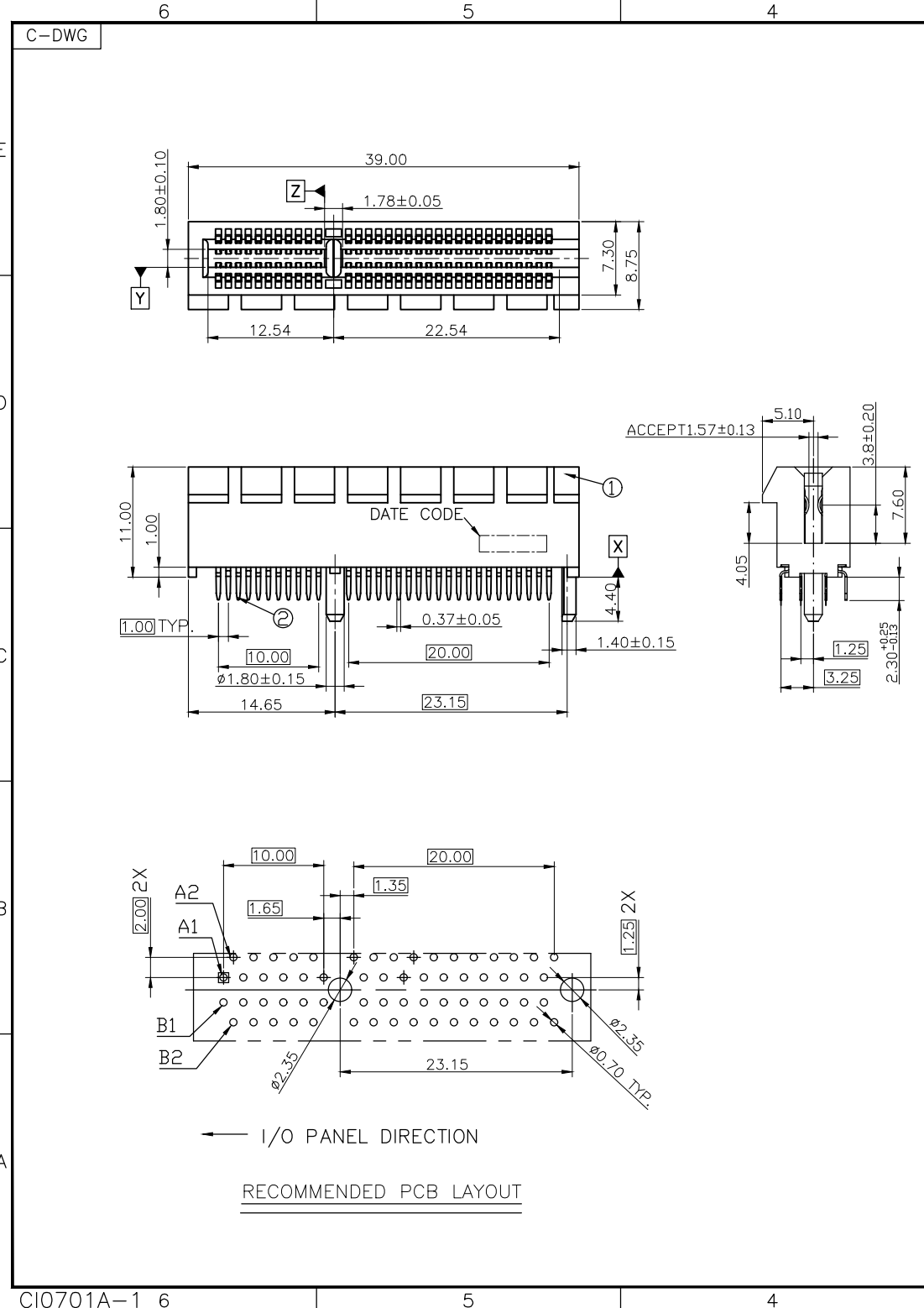




REV.	ECN NO.	DESCRIPTION	DATE	DESIGN
04	--	Change Stand off	2022.02.24	Alan
05	--	Add package specification	2022.05.07	Alan

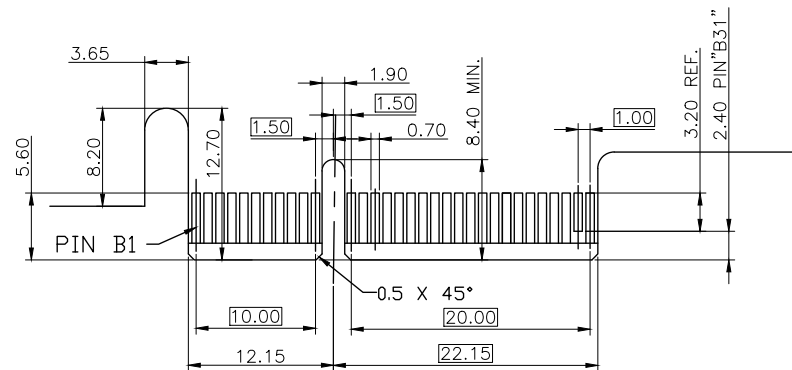
NOTES:

- ELECTRICAL CHARACTERISTICS:
 - 1-1 CURRENT RATING: 1.1 A MAX. PER PIN, 30°C RISE ABOVE AMBIENT.
 - 1-2 CONTACT RESISTANCE: 30 MILLIOHMS MAX. INITIAL, 50 MILLIOHMS MAX. AFTER TEST.
 - 1-3 INSULATION RESISTANCE: 1000 MEGOHMS MIN..
 - 1-4 DIELECTRICAL WITHSTAND VOLTAGE: 500 V AC MIN. AT SEA LEVEL.
- MECHANICAL CHARACTERISTICS:
 - 2-1 CONTACT INSERTION FORCE: 1.15 N MAX. PER CONTACT PAIR.
 - 2-2 CONTACT REMOVAL FORCE: 0.15 N MIN. PER CONTACT PAIR.
 - 2-3 DURABILITY: 50 MATING AND UNMATING CYCLES.
 - 2-4 CONTACT RETENTION FORCE: 4.9 N MIN. PER PIN.
- ENVIRONMENTAL CHARACTERISTICS:
 - 3-1 OPERATING TEMPERATURE RANGE: -40°C TO +105°C .
- RECOMMENDED PROCESS CONDITION: WAVE SOLDER , 260°C , 3~5S.
- HF COMPLIANT.
- PART NO.

121P-C4E B - B3 * T
T:TRAY
G:G/F 1:1u" 5:5u" A:10u" B:15u" C:30u"
FLOWING WATER CODE
HOUSING COLOR:
B: BLACK

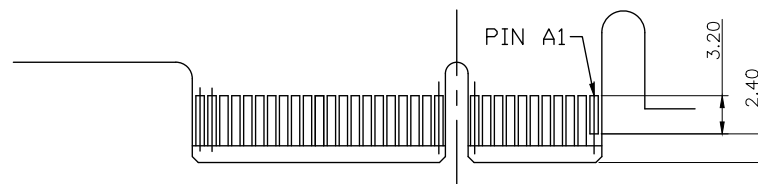
2	CONTACT	64	COPPER ALLOY	50u" MIN. NICKEL PLATING OVERALL UNDERPLATED 100u" MIN. TIN PLATING ON SOLDER TAIL AREA, GOLD PLATING ON CONTACT AREA
1	HOUSING	1	THERMOPLASTIC PA10T UL 94V-0	MOLDED BLACK
ITEM	DESCRIPTION	QYP.	MATERIAL	TREATMENT
DIM	TOL	DIM	DEG	JOINSOO建舜電子
X	±0.50	X°	±8°	
X.X	±0.35	X.X°	±5°	
X.XX	±0.25	X.XX°	±3°	
X.XXX	±0.15	X.XXX°	±2°	
DESIGN:	ALAN	2022.05.07	FILE: -	DRAW NAME:
CHECK:			DRAW NO. -	PCI-E GEN3.0 X4 64P
APPROVED			P/N: 121P-C4EB-B3*T	
			UNIT: mm	SCALE: 1:1
			REV: 05	SHEET: 1/3
				MODEL:

REV.	ECN NO.	DESCRIPTION	DATE	DESIGN
04	--	Change Stand off	2022.02.24	Alan
05	--	Add package specification	2022.05.07	Alan



← I/O PANEL DIRECTION

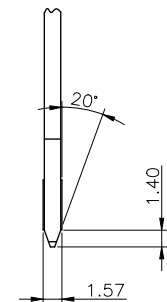
PRIMARY (COMPONENT) SIDE



I/O PANEL DIRECTION →

SECONDARY (SOLDER) SIDE

ADD-IN CARD EDGE-FINGER DIMENSIONS



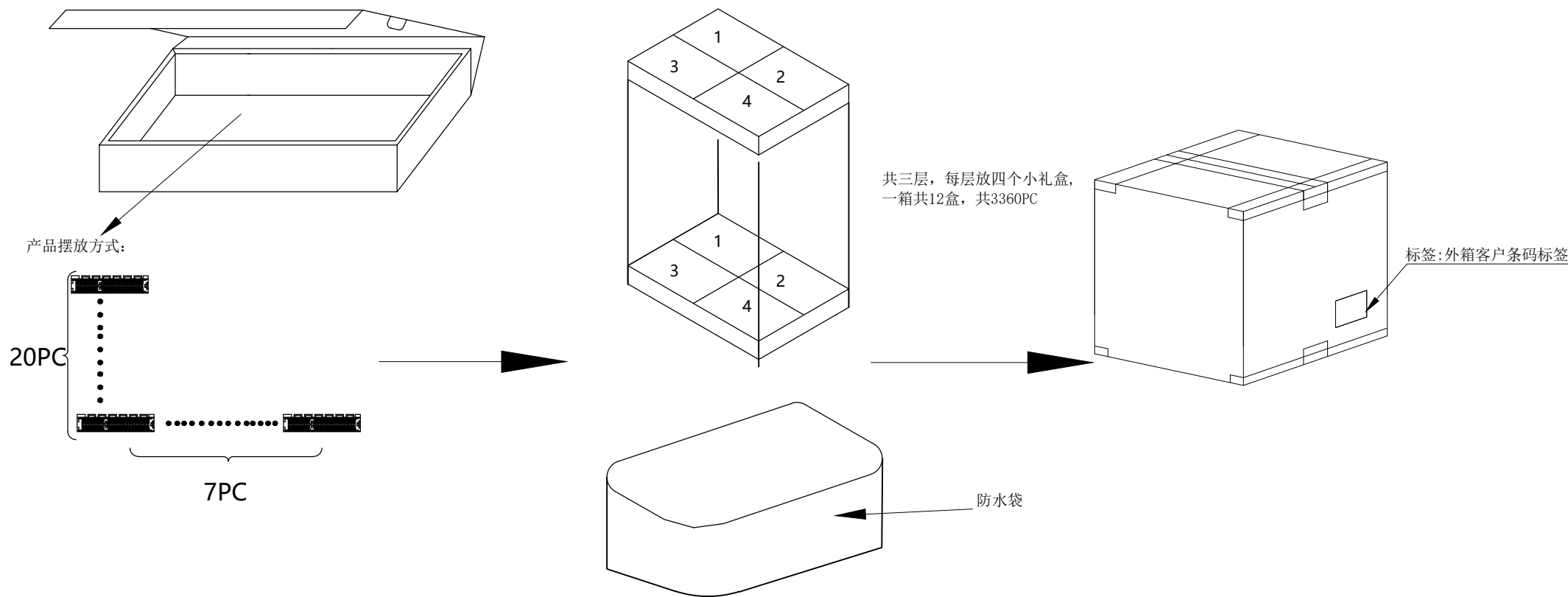
ACROSS PADS

NOTES:

1. NO TIE BAR PERMITTED FROM CARD EDGE TO LEADING EDGE OF PAD FOR PINS A1 AND 'B31'.
2. CHAMFER EDGES MUST BE FREE OF CUTTING BURRS.

DIM		TOL	DIM		DEG	JOINSOO建舜電子			
X		±0.50	X*		±8°	FILE: - DRAW NAME: DRAW NO. - P/N: 121P-C4EB-B3*T UNIT: mm SCALE: 1:1 REV: 05 SHEET: 2/3			
X.X		±0.35	X.X*		±5°				
X.XX		±0.25	X.XX*		±3°				
X.XXX		±0.15	X.XXX*		±2°				
DESIGN:		ALAN		2022.05.07		PCI-E GEN3.0 X4 64P			
CHECK:									
APPROVED						MODEL:			

REV.	ECN NO.	DESCRIPTION	DATE	DESIGN
04	--	Change Stand off	2022.02.24	Alan
05	--	Add package specification	2022.05.07	Alan



1. 共摆放两层，一盒装满数量为280PC。
2. 共12盒放入防水袋中，一箱装满数量为3360PC。
3. 封箱张贴标签，尾数箱张贴“尾数”标签。

DIM	TOL	DIM	DEG	JOINSOO建舜電子		
X	±0.50	X°	±8°	FILE: - DRAW NAME: DRAW NO. - P/N: 121P-C4EB-B3*T UNIT: mm SCALE: 1:1 REV: 05 SHEET: 3/3		
X.X	±0.35	X.X°	±5°			
X.XX	±0.25	X.XX°	±3°			
X.XXX	±0.15	X.XXX°	±2°			
DESIGN:	ALAN	2022.05.07	PCI-E GEN3.0 X4 64P			
CHECK:			MODEL:			
APPROVED			- 			